

REMARKS

Claims 1-8 and 21-32 are pending.

Claims 1, 3, 21 and 30-32 are rejected under 35 U.S.C 103 (a) as being unpatentable over Yang et al. (U.S. Patent No. 6,207,248).

Yang discloses reactive hot melt polyurethane adhesives. In contrast to hot melt adhesives that can be repeatedly heated from its solid state and flowed to a liquid form, reactive hot melt adhesives, also referred to in the art as polyurethane hot melt adhesives, contain isocyanate terminated prepolymers that react with surface or ambient moisture in order to chain-extend forming a new polyurethane polymer. Reactive hot melt adhesives go through an irreversible chemical reaction once dispensed in the presence of ambient moisture. While the reactive hot melts of Yang may contain additives such as tackifying resins and thermoplastic polymers, the additives are still reactive polyurethane hot melt adhesives and thus contain a polyfunctional isocyanate component and a polymer polyol component. Yang does not disclose or suggest a hot melt adhesive that is not a reactive polyurethane hot melt. Applicants' claimed invention does not encompass reactive hot melts and do not contain polyurethane components. Reconsideration and withdrawal of the rejection over Yang is requested.

Claims 2 and 22 are rejected under 35 U.S.C 103 (a) as being unpatentable over Yang et al. (U.S. Patent No. 6,207,248) in view of Milks (U.S. Patent No. 5,401,791).

The disclosure of Milks fails to cure the defect of Yang by suggesting a hot melt adhesive, which is not a reactive hot melt, comprising an ethylene n-butyl acrylate copolymer, a modified terpene tackifier for use in bonding difficult to bond substrates such as UV varnish

treated substrates, acrylic varnish treated substrates and fluorochemical treated substrates.

Reconsideration and withdraw of the rejection over Yang in view of Milks is requested.

Claims 4, 5, 23 and 24 are rejected under 35 U.S.C 103 (a) as being unpatentable over Yang et al. (U.S. Patent No. 6,207,248) in view of Dupont et al. (U.S. Patent No. 5,325,781).

The disclosure of Dupont fails to cure the defect of Yang by suggesting a hot melt adhesive, which is not a reactive hot melt, comprising an ethylene n-butyl acrylate copolymer, a modified terpene tackifier for use in bonding difficult to bond substrates such as UV varnish treated substrates, acrylic varnish treated substrates and fluorochemical treated substrates. Reconsideration and withdraw of the rejection over Yang in view of Dupont is requested.

Claims 6-8 and 25-27 are rejected under 35 U.S.C 103 (a) as being unpatentable over Yang et al. (U.S. Patent No. 6,207,248) in view of Howells (U.S. Patent No. 4,566,981).

The disclosure of Howells fails to cure the defect of Yang by suggesting a hot melt adhesive, which is not a reactive hot melt, comprising an ethylene n-butyl acrylate copolymer, a modified terpene tackifier for use in bonding difficult to bond substrates such as UV varnish treated substrates, acrylic varnish treated substrates and fluorochemical treated substrates. Reconsideration and withdraw of the rejection over Yang in view of Howells is requested.

Claims 28-29 and 22 are rejected under 35 U.S.C 103 (a) as being unpatentable over Yang et al. (U.S. Patent No. 6,207,248) in view of Gruber et al. (U.S. Patent No. 5,475,080).

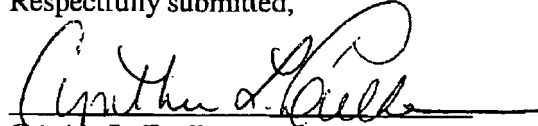
The disclosure of Gruber fails to cure the defect of Yang by suggesting a hot melt adhesive, which is not a reactive hot melt, comprising an ethylene n-butyl acrylate copolymer, a modified terpene tackifier for use in bonding difficult to bond substrates such as UV varnish

treated substrates, acrylic varnish treated substrates and fluorochemical treated substrates.

Reconsideration and withdraw of the rejections over Yang in view of Gruber is requested.

Favorable reconsideration and an early notification of allowance are solicited.

Respectfully submitted,



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